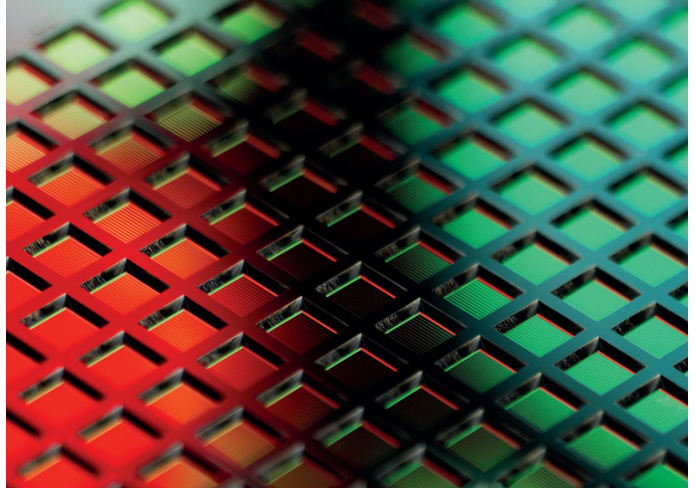


We offer custom solutions to OEM manufacturers ranging from concept to full scale volume manufacturing. Our facilities include a class 100 clean room environment, lithography and thin film processing. Our high standard of quality control is ensured by a suite of metrological systems and the use of modern statistical methods which underpin all of our production processes. As an ISO 9001:2008 certified company, we ensure the highest level of quality at a consistent level.



Axetris standard capabilities

Photolithography

- Photolithography of 1 μm for up to 8" wafers
- Single or double sided alignment
- Thick resist processing (SU8, others)
- Spray coating on severe topographies

Wet Etching

- Anisotropic Silicon etching
- Glass etching
- Metal etching

Metallization

- Sputtering up to 8" wafers

Dielectric coating deposition

- Silicon oxides and nitrides by PECVD
- Oxides or nitrides by reactive sputtering

Reactive Ion Etching

- Fused Silica
- Silicon
- Silicon Nitride / Oxide
- Photoresist

Metrology and characterization

- Interferometric and tactile surface measurements
- Film thickness measurement
- Resistivity & resistance
- Optical microscopy
- Scanning electron microscopy (SEM)

Axetris special capabilities

Micro-optics

- Refractive and diffractive micro-optical elements

Thin membranes

- Thin dielectric membranes for optics, sensors and life science applications

CMOS wafers post processing

- CMOS post processing like back side openings, metallization, thin film deposition

Lift-Off Processes

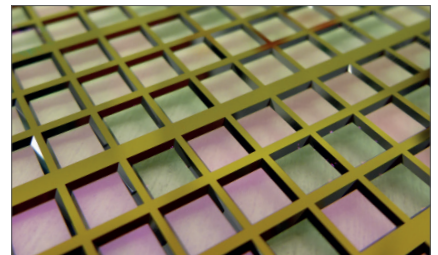
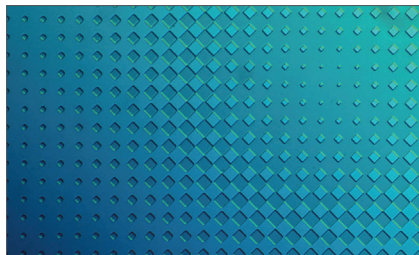
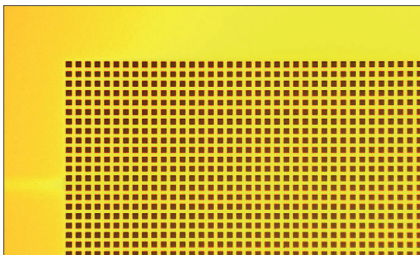
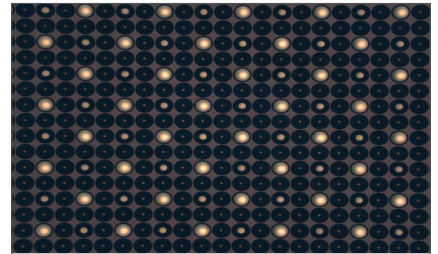
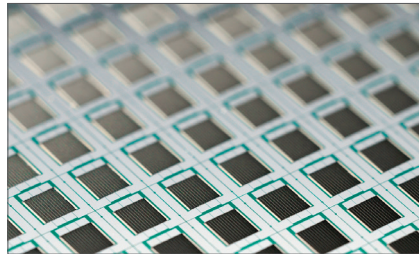
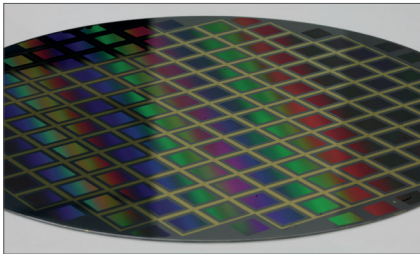
- Metallization in connection with lift off processes for electrode formation or solder pad definition. Materials include Au, Pt, AuSn, Cr, Ni, Ta, TiW, Cu, Al, other materials upon request

Dicing

- Dicing of Silicon, glass & fused silica wafers
- Dicing of chips with fragile structures such as thin membranes and micro-optic structures

Wet etching of glass

- Wet etching processes for microfluidics, optics and encapsulation



About Axetris AG

Axetris AG, a company of the Leister group, is serving OEM customers with micro-optical components used in telecom and industrial applications, and micro-technology based (MEMS) infrared light sources, laser gas sensors, mass flow sensors and controllers.

Axetris supports its customers in many industries with in-depth application know-how. Our engineering and manufacturing teams combine broad experience in simulation, design, manufacturing and metrology from microchip level to advanced electronic and electro-optic modules.

Customers benefit from excellent product value, consistent high product quality and outstanding customer support. OEMs rely on Axetris as a competent partner for a wide range of high-quality off-the shelf products as well as customer specific solutions from concept to volume production.

Axetris is ISO 9001 certified and ISO TS 16949 compliant and operates its own 6" to 8" wafer MEMS foundry in Central Switzerland for its own products and external customers.



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Swiss Made Quality. Axetris is an ISO 9001 certified enterprise.